# **Dual Up Counters**

The MC14518B dual BCD counter and the MC14520B dual binary counter are constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. Each consists of two identical, independent, internally synchronous 4-stage counters. The counter stages are type D flip-flops, with interchangeable Clock and Enable lines for incrementing on either the positive-going or negative-going transition as required when cascading multiple stages. Each counter can be cleared by applying a high level on the Reset line. In addition, the MC14518B will count out of all undefined states within two clock periods. These complementary MOS up counters find primary use in multi-stage synchronous or ripple counting applications requiring low power dissipation and/or high noise immunity.

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Internally Synchronous for High Internal and External Speeds
- Logic Edge-Clocked Design Incremented on Positive Transition of Clock or Negative Transition on Enable
- Capable of Driving Two Low–power TTL Loads or One Low–power Schottky TTL Load Over the Rated Temperature Range

# MAXIMUM RATINGS (Voltages Referenced to V<sub>SS</sub>) (Note 2.)

Symbol	Parameter	Value	Unit
$V_{DD}$	DC Supply Voltage Range	-0.5 to +18.0	V
V <sub>in</sub> , V <sub>out</sub>	Input or Output Voltage Range (DC or Transient)	-0.5 to V <sub>DD</sub> + 0.5	V
I <sub>in</sub> , I <sub>out</sub>	Input or Output Current (DC or Transient) per Pin	±10	mA
P <sub>D</sub>	Power Dissipation, per Package (Note 3.)	500	mW
T <sub>A</sub>	Operating Temperature Range	-55 to +125	°C
T <sub>stg</sub>	Storage Temperature Range	-65 to +150	°C
T <sub>L</sub>	Lead Temperature (8–Second Soldering)	260	°C

- Maximum Ratings are those values beyond which damage to the device may occur.
- Temperature Derating: Plastic "P and D/DW" Packages: – 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ). Unused outputs must be left open.

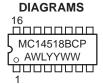


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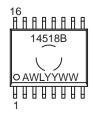
PDIP-16 P SUFFIX CASE 648



**MARKING** 

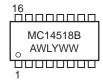


SOIC-16 DW SUFFIX CASE 751G





SOEIAJ-16 F SUFFIX CASE 966



A = Assembly Location

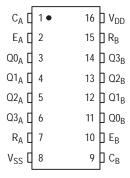
WL or L = Wafer Lot YY or Y = Year WW or W = Work Week

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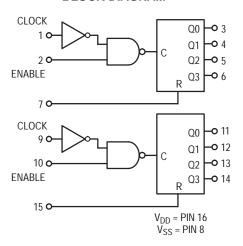
Device	Package	Shipping		
MC14518BCP	PDIP-16	2000/Box		
MC14518BDW	SOIC-16	47/Rail		
MC14518BDWR2	SOIC-16	1000/Tape & Reel		
MC14518BF	SOEIAJ-16	See Note 1.		
MC14518BFEL	SOEIAJ-16	See Note 1.		

 For ordering information on the EIAJ version of the SOIC packages, please contact your local ON Semiconductor representative.

## **PIN ASSIGNMENT**



## **BLOCK DIAGRAM**



# **TRUTH TABLE**

Clock	Enable	Reset	Action		
	1	0	Increment Counter		
0	~	0	Increment Counter		
$\overline{}$	Х	0	No Change		
Х		0	No Change		
	0	0	No Change		
1	~	0	No Change		
Х	Х	1	Q0 thru Q3 = 0		

X = Don't Care

## **ELECTRICAL CHARACTERISTICS** (Voltages Referenced to V<sub>SS</sub>)

			V <sub>DD</sub>	- 5	5°C		25°C		125	5°C	
Characteristic		Symbol	Vdc	Min	Max	Min	Typ <sup>(4.)</sup>	Max	Min	Max	Unit
Output Voltage V <sub>in</sub> = V <sub>DD</sub> or 0	"0" Level	V <sub>OL</sub>	5.0 10 15	_ _ _	0.05 0.05 0.05	_ _ _	0 0 0	0.05 0.05 0.05	_ _ _	0.05 0.05 0.05	Vdc
V <sub>in</sub> = 0 or V <sub>DD</sub>	"1" Level	V <sub>OH</sub>	5.0 10 15	4.95 9.95 14.95	_ _ _	4.95 9.95 14.95	5.0 10 15	_ _ _	4.95 9.95 14.95	_ _ _	Vdc
Input Voltage $(V_O = 4.5 \text{ or } 0.5 \text{ Vdc})$ $(V_O = 9.0 \text{ or } 1.0 \text{ Vdc})$ $(V_O = 13.5 \text{ or } 1.5 \text{ Vdc})$	"0" Level	V <sub>IL</sub>	5.0 10 15		1.5 3.0 4.0		2.25 4.50 6.75	1.5 3.0 4.0		1.5 3.0 4.0	Vdc
$(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	"1" Level	V <sub>IH</sub>	5.0 10 15	3.5 7.0 11	_ _ _	3.5 7.0 11	2.75 5.50 8.25	_ _ _	3.5 7.0 11	_ _ _	Vdc
Output Drive Current $(V_{OH} = 2.5 \text{ Vdc})$ $(V_{OH} = 4.6 \text{ Vdc})$ $(V_{OH} = 9.5 \text{ Vdc})$ $(V_{OH} = 13.5 \text{ Vdc})$	Source	I <sub>OH</sub>	5.0 5.0 10 15	-3.0 -0.64 -1.6 -4.2	_ _ _ _	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	_ _ _ _	- 1.7 - 0.36 - 0.9 - 2.4	_ _ _ _	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	I <sub>OL</sub>	5.0 10 15	0.64 1.6 4.2	_ _ _	0.51 1.3 3.4	0.88 2.25 8.8	_ _ _	0.36 0.9 2.4	_ _ _	mAdc
Input Current		l <sub>in</sub>	15	_	± 0.1	_	±0.00001	± 0.1		± 1.0	μAdc
Input Capacitance (V <sub>in</sub> = 0)		C <sub>in</sub>	_	_	_	_	5.0	7.5	_	_	pF
Quiescent Current (Per Package)		I <sub>DD</sub>	5.0 10 15	_ _ _	5.0 10 20	_ _ _	0.005 0.010 0.015	5.0 10 20	_ _ _	150 300 600	μAdc
Total Supply Current <sup>(5.)</sup> (6 (Dynamic plus Quiesco Per Package) (C <sub>L</sub> = 50 pF on all outp buffers switching)	ent,	I <sub>T</sub>	5.0 10 15			$I_{T} = (1$	).6 μΑ/kHz) f l.2 μΑ/kHz) f l.7 μΑ/kHz) f	+ I <sub>DD</sub>	•		μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where:  $I_T$  is in  $\mu A$  (per package),  $C_L$  in pF,  $V = (V_{DD} - V_{SS})$  in volts, f in kHz is input frequency, and k = 0.002.

# SWITCHING CHARACTERISTICS (7.) $(C_L = 50 \text{ pF}, T_A = 25^{\circ}\text{C})$

			All Types			
Characteristic	Symbol	V <sub>DD</sub>	Min	Тур (8.)	Max	Unit
Output Rise and Fall Time $t_{TLH}, t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns} \\ t_{TLH}, t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns} \\ t_{TLH}, t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns} \\ \end{cases}$	t <sub>TLH</sub> , t <sub>THL</sub>	5.0 10 15	_ _ _	100 50 40	200 100 80	ns
Propagation Delay Time Clock to Q/Enable to Q $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 215 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 97 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 75 \text{ ns}$	t <sub>PLH</sub> , t <sub>PHL</sub>	5.0 10 15	_ _ _	280 115 80	560 230 160	ns
Reset to Q $t_{PHL}$ = (1.7 ns/pF) $C_L$ + 265 ns $t_{PHL}$ = (0.66 ns/pF) $C_L$ + 117 ns $t_{PHL}$ = (0.66 ns/pF) $C_L$ + 95 ns	t <sub>PHL</sub>	5.0 10 15	_ _ _	330 130 90	650 230 170	ns
Clock Pulse Width	t <sub>w(H)</sub> t <sub>w(L)</sub>	5.0 10 15	200 100 70	100 50 35	_ _ _	ns
Clock Pulse Frequency	f <sub>cl</sub>	5.0 10 15	_ _ _	2.5 6.0 8.0	1.5 3.0 4.0	MHz
Clock or Enable Rise and Fall Time	t <sub>THL</sub> , t <sub>TLH</sub>	5.0 10 15	_ _ _	_ _ _	15 5 4	μѕ
Enable Pulse Width	t <sub>WH(E)</sub>	5.0 10 15	440 200 140	220 100 70	_ _ _	ns
Reset Pulse Width	t <sub>WH(R)</sub>	5.0 10 15	280 120 90	125 55 40	_ _ _	ns
Reset Removal Time	t <sub>rem</sub>	5.0 10 15	- 5 15 20	- 45 - 15 - 5	_ _ _	ns

<sup>7.</sup> The formulas given are for the typical characteristics only at 25°C.
8. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

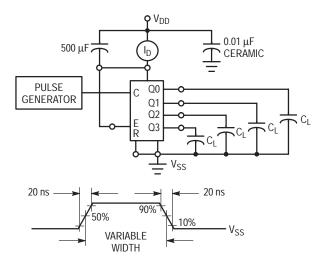


Figure 1. Power Dissipation Test Circuit and Waveform

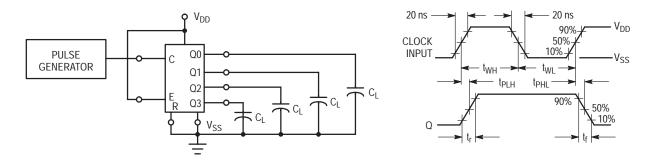


Figure 2. Switching Time Test Circuit and Waveforms

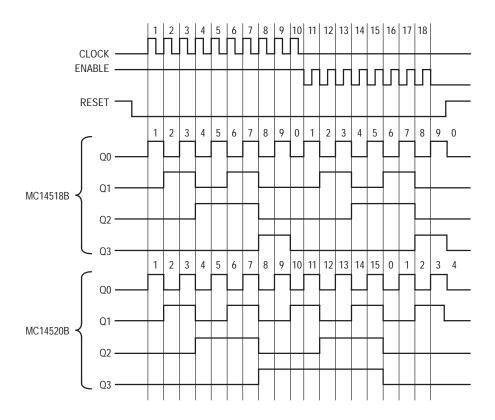


Figure 3. Timing Diagram

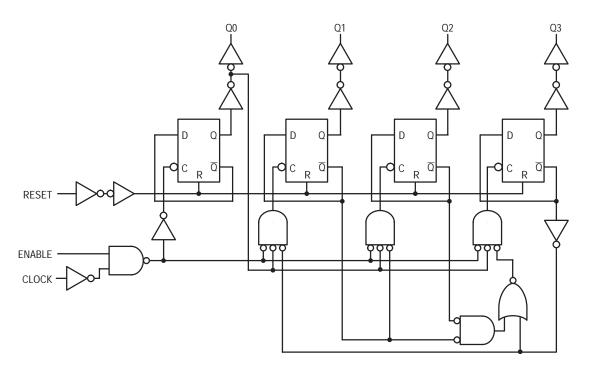


Figure 4. Decade Counter (MC14518B) Logic Diagram (1/2 of Device Shown)

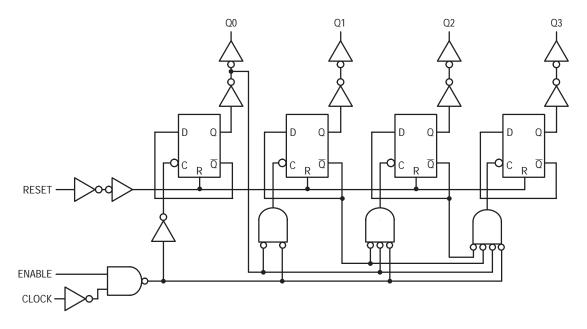
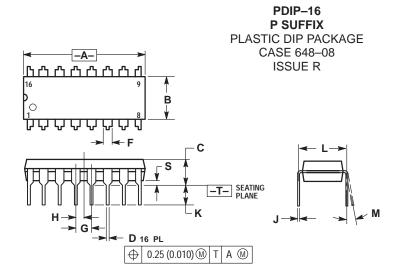


Figure 5. Binary Counter (MC14520B) Logic Diagram (1/2 of Device Shown)

## **PACKAGE DIMENSIONS**



#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: INCH.

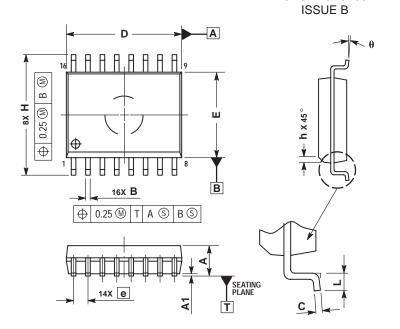
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

  5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100	0.100 BSC		BSC
Н	0.050	BSC	1.27	BSC
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10 °	0°	10 °
S	0.020	0.040	0.51	1.01

### SOIC-16 **DW SUFFIX** PLASTIC SOIC PACKAGE CASE 751G-03



#### NOTES:

- IOTES:

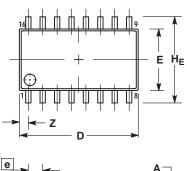
  1. DIMENSIONS ARE IN MILLIMETERS.
  2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
  3. DIMENSIONS D AND E DO NOT INLCUDE MOLD
- PROTRUSION.

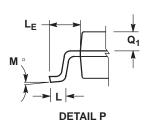
  4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
- DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR
  PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS
  OF THE B DIMENSION AT MAXIMUM MATERIAL
  CONDITION.

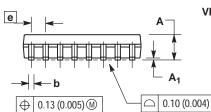
	MILLIMETERS				
DIM	MIN	MAX			
Α	2.35	2.65			
A1	0.10	0.25			
В	0.35	0.49			
С	0.23	0.32			
D	10.15	10.45			
Ε	7.40	7.60			
е	1.27	BSC			
Н	10.05	10.55			
h	0.25	0.75			
L	0.50	0.90			
Δ	U o	70			

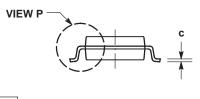
#### PACKAGE DIMENSIONS

### SOEIAJ-16 **F SUFFIX** PLASTIC EIAJ SOIC PACKAGE CASE 966-01 **ISSUE O**









#### NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14 5M 1982
- CONTROLLING DIMENSION: MILLIMETER. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

  I. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.

  THE LEAD WIDTH DIMENSION (b) DOES NOT

TO BE 0.46 (0.018).

INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE
BETWEEN PROTRUSIONS AND ADJACENT LEAD

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
Α <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
Ε	5.10	5.45	0.201	0.215
е	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
$Q_1$	0.70	0.90	0.028	0.035
Z		0.78		0.031

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MC14518B/D